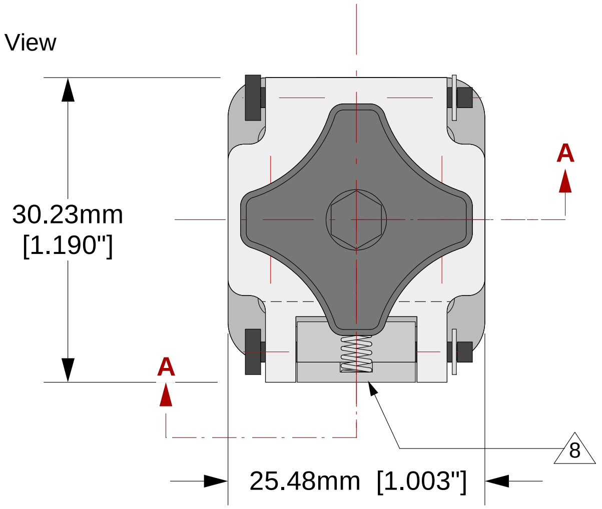
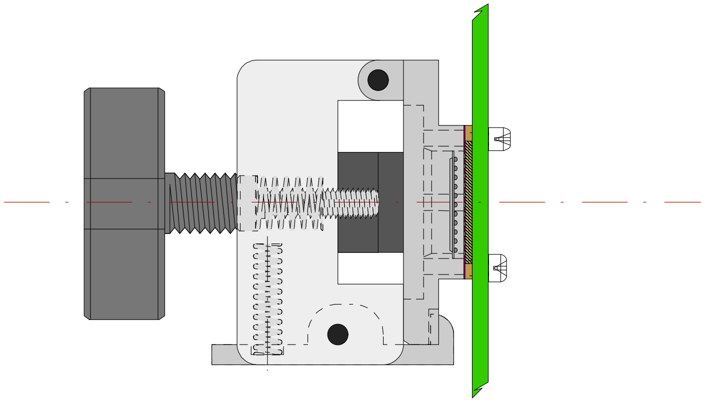
Top View





Features

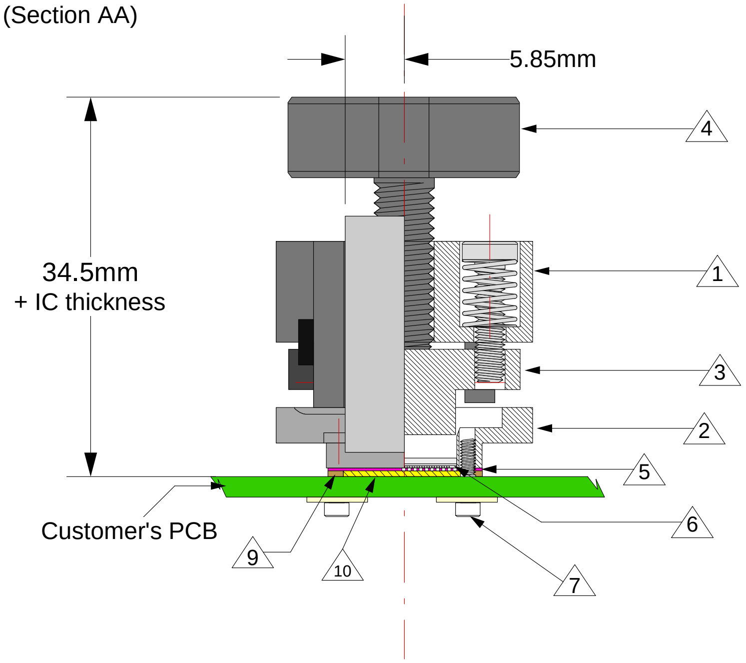
Directly mounts to target PCB (needs tooling holes) with hardware

Minimum real estate required

Compression plate distributes forces evenly

Clamshell lid

Side View
(Section AA)



Materials:

1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.

2 Socket Base: Black anodized Aluminum. Height = 6 mm.

3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.

4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob

5 Ball Guide: Kapton polyimide.

6 Customer's BGA IC

7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 1/4" long.

8 Latch: Black anodised Aluminum.

9 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.

10 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.

CG-BGA-4009 Drawing	Status: Released	Scale: -	Rev:A
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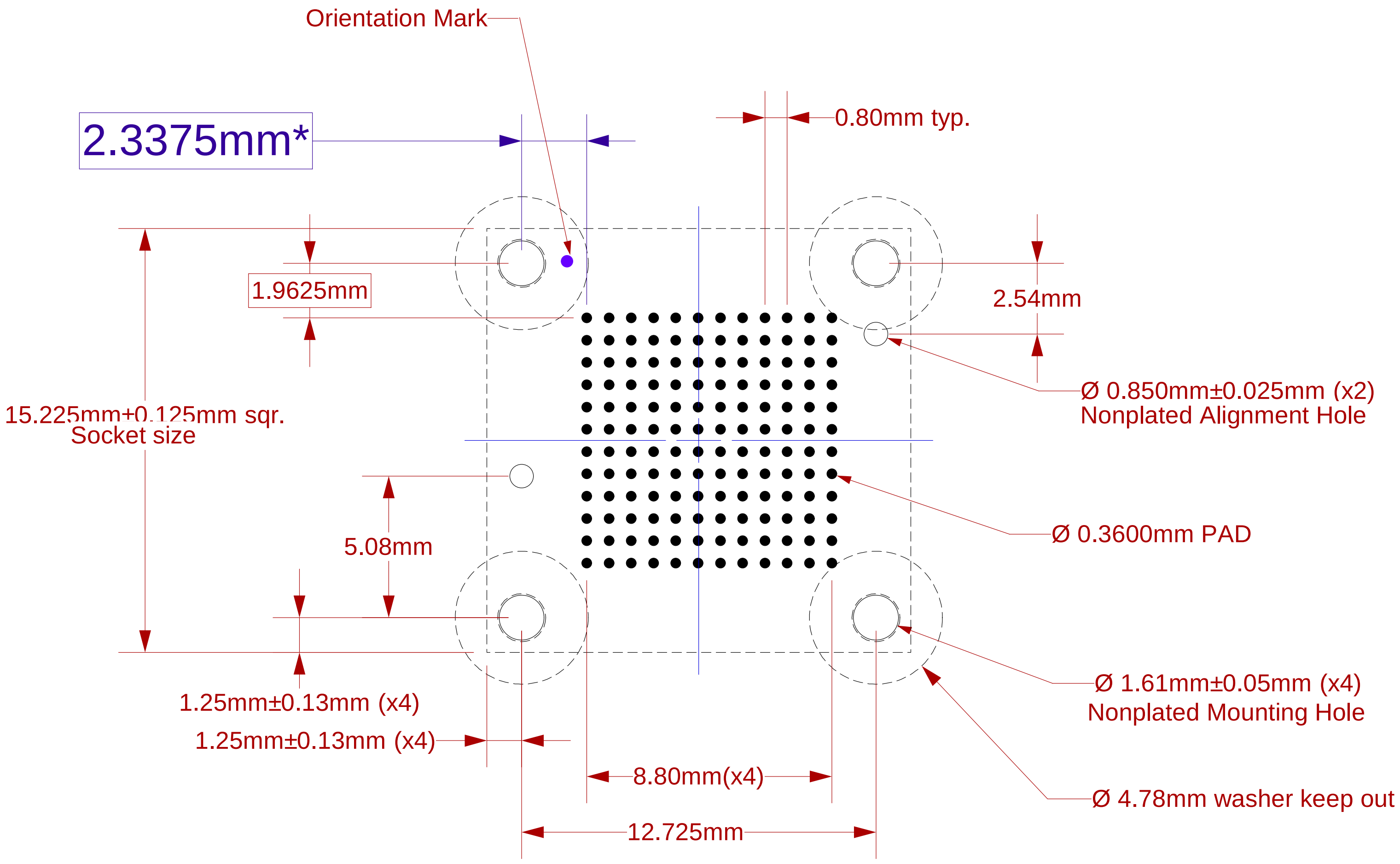
	File: CG-BGA-4009 Dwg.mcd	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

Note: BGA pattern is not symmetrical with respect to the mounting holes.



Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001”] unless stated otherwise.

CG-BGA-4009 Drawing	Status: Released	Scale: 4:1	Rev:A
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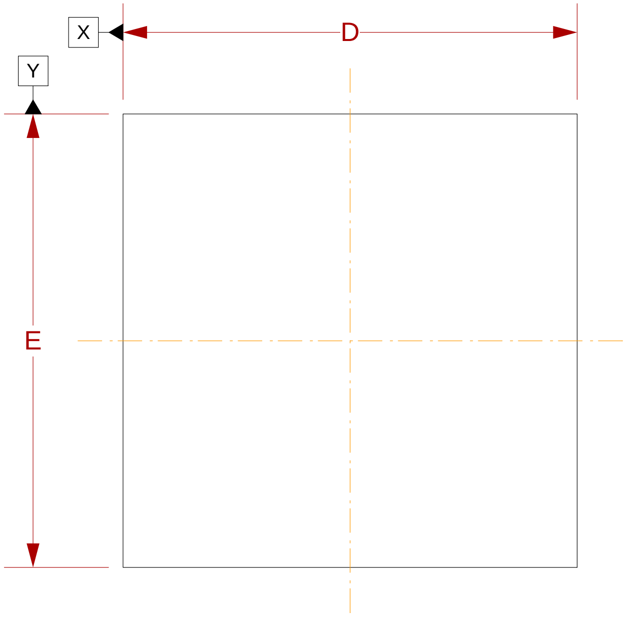
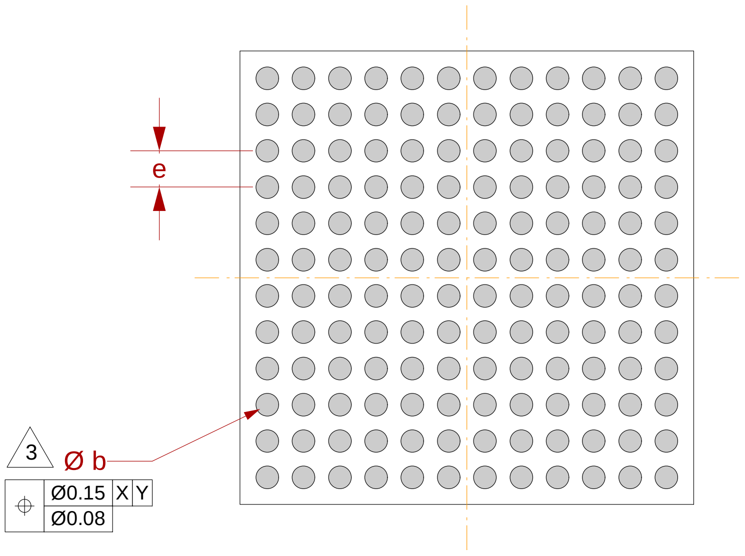
	File: CG-BGA-4009 Dwg.mcd	Modified:	

Recommended PCB Layout Tolerances:
±0.025mm [±0.001”] unless stated otherwise.

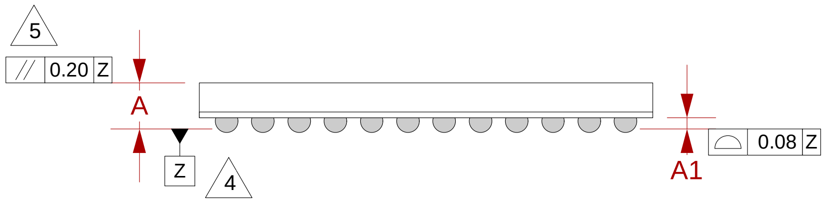
Compatible BGA Spec



Top View



Bottom View



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.25	0.35
b		0.6
D	10.0 BSC	
E	10.0 BSC	
e	0.8 BSC	

Array: 12x12

CG-BGA-4009 Drawing	Status: Released	Scale: -	Rev:A
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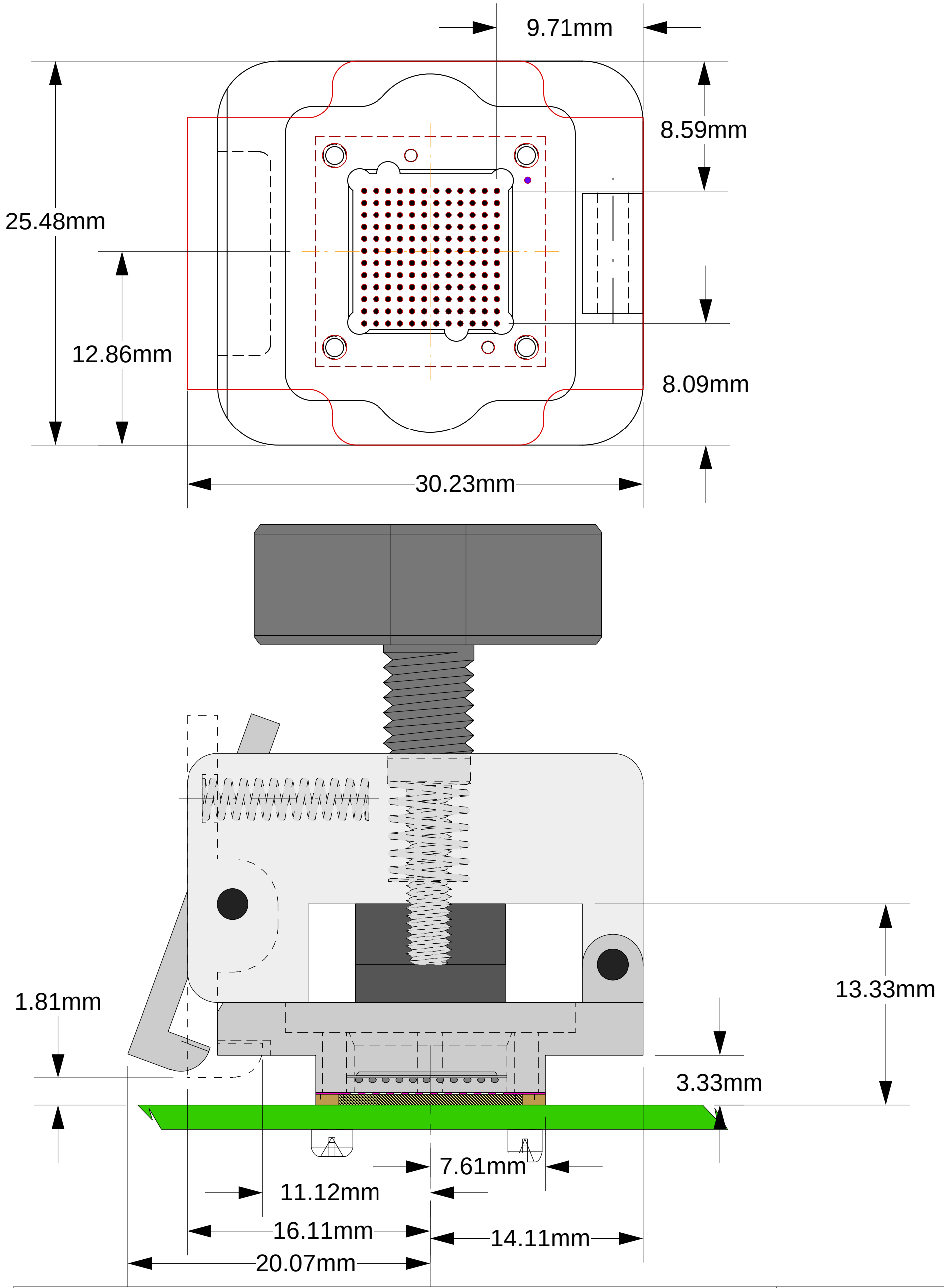

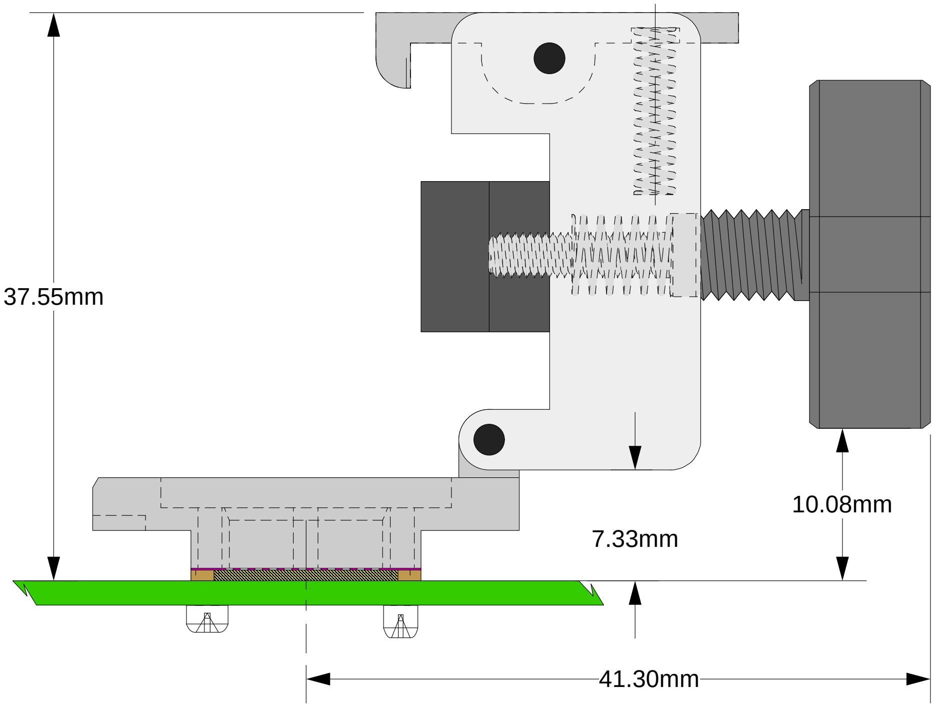

CG-BGA-4009 Drawing

Status: Released

Scale: -

Rev:A

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Modified: